

SPECIFICATIONS

	: -		
SAMPLE CODE		RC0802LRS-LWA-B	
		(This Code will be changed while	mass production)
MASS PRODUCTION	N CODE :		
	Customer	Approved	
	Customer	Approved Date:	
	Customer		
Sales Sign QC	Customer C Confirmed		Designe
Sales Sign QC		Date:	Designe
Sales Sign QC		Date:	Designe
Sales Sign QC		Date:	Designe

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RECORDS OF REVISION

Date	Rev.	Description	Note	Page
2003/05/29	0	Revised Contents		
2003/06/23	A	Update Storage Humidity(max)=90 %RH		4

Total: 20 Page



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Note: For detailed information please refer to IC data sheet: <u>ST7066U</u>



1. SPECIFICATIONS

1.1 Features

Item	Standard Value
Display Type	8*2 Characters
LCD Type	STN Gray Positive Transflective Normal Temp.
Driver Condition	LCD Module: 1/16 Duty, 1/5 Bias
Viewing Direction	6 O' clock
Backlight	YG LED B/L
Weight	46 g
Interface	-
Other	_

1.2 Mechanical Specifications

Item	Standard Value	Unit
Outline Dimension	84.0(L) * 44.0 (w) * 14.2 (H)(Max)	mm
Viewing Area	63.0(L) * 25.0 (w)	mm
Active Area	57.17(L) * 23.0 (w)	mm
Dot Size	1.15(L) * 1.36 (w)	mm
Dot Pitch	1.23(L) * 1.44 (w)	mm

Note: For detailed information please refer to LCM drawing

1.3 Absolute Maximum Ratings

Item	Symbol	Condition	Min.	Max.	Unit
Power Supply Voltage	V_{DD}	_	-0.3	7.0	V
LCD Driver Supply Voltage	V_{LCD}	_	VDD-10.0	V _{DD} +0.3	V
Input Voltage	V_{IN}	_	-0.3	V _{DD} +0.3	V
Operating Temperature	T_{OP}	Excluded B/L	0	50	°C
Storage Temperature	T_{ST}	Excluded B/L	-20	70	°C
Storage Humidity	H_D	Ta<40 °C	-	90	%RH



1.4 DC Electrical Characteristics

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Logic Supply Voltage	V_{DD}	1	4.5	5.0	5.5	V
"H" Input Voltage	$ m V_{IH}$	ĺ	0.7 VDD	ı	VDD	V
"L" Input Voltage	V_{IL}	1	-0.3	ı	0.6	V
"H" Output Voltage	V_{OH}	Iон=-0.1mА	3.9	ı	VDD	V
"L" Output Voltage	V_{OL}	IOL=0.1mA	-	1	0.4	V
Supply Current	I_{DD}	$V_{DD} = 5.0 \text{ V}$	-	1.0	-	mA
		V_{DD} - V_{O} (0°C)	-	ı	•	
LCM Driver Voltage	$ m V_{OP}$	V _{DD} - V _O (25°C)	-	4.0	-	V
		$ m V_{DD}$ - $ m V_O$ (50°C)	-	-	-	

1.5 Optical Characteristics

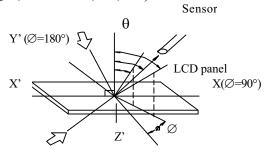
LCD Panel : 1/16 Duty • 1/5 Bias • V_{LCD} =4.76 V • Ta = 25°C

				ECE		
Item	Symbol	Conditions	Min.	Тур.	Max.	Reference
View Angle	è	$C \ge 2.0, \varnothing = 0^{\circ}$	40°	-	-	Notes 1 & 2
Contrast Ratio	С	$\grave{e} = 5^{\circ}, \varnothing = 0^{\circ}$	5	7	-	Note 3
Response Time(rise)	tr	$\grave{e} = 5^{\circ}, \varnothing = 0^{\circ}$	-	150 ms	-	Note 4
Response Time(fall)	tf	è = 5°, ∅ = 0°	-	300 ms	-	Note 4



Note 1: Definition of angles θ and \emptyset

Light (when reflected) $z (\theta=0^{\circ})$



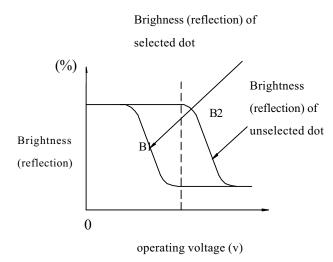
Light (when transmitted) $Y(\varnothing=0^{\circ})$ $(\theta=90^{\circ})$

Note 3: Definition of contrast C

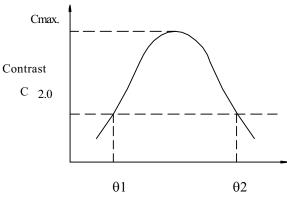
C = -

Brightness (reflection) of unselected dot (B2)

Brightness (reflection) of selected dot (B1)



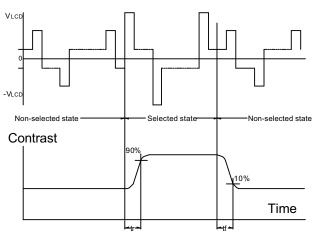
Note 2: Definition of viewing angles $\theta 1$ and $\theta 2$



viewing angle θ (\emptyset fixed)

Note : Optimum viewing angle with the naked eye and viewing angle θ at Cmax. Above are not always the same

Note 4: Definition of response time



Note: Measured with a transmissive LCD panel which is displayed 1 cm²

 V_{LCD} : Operating voltage f_{FRM} : Frame frequency t_r : Response time (rise) t_f : Response time (fall)



1.6 Backlight Characteristics

LCD Module with LED Backlight

Maximum Ratings

Item	Symbol	Conditions	Min.	Max.	Unit
Forward Current	IF	Ta =25°C	-	550	mA
Reverse Voltage	VR	Ta =25°C	-	8	V
Power Dissipation	PO	Ta =25°C	-	2.53	W
Operating Temperature	T _{OP}	-	-20	70	$^{\circ}\mathbb{C}$
Storage Temperature	T_{ST}	-	-40	80	$^{\circ}\mathbb{C}$
Solder Temp. for 3 Second	-	-	-	260	$^{\circ}\mathbb{C}$

Electrical / Optical Characteristics

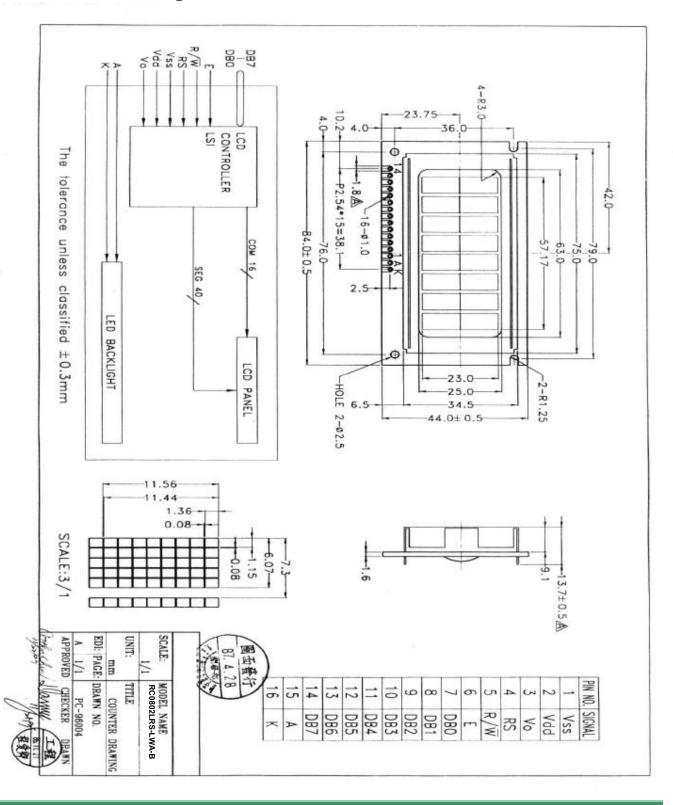
Ta =25°C

Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Voltage	VF	IF=220 mA	-	4.2	4.6	V
Reverse Current	IR	VR=8V	-	-	0.2	mA
Average Brightness (with LCD)	IV	IF=220 mA	-	-	-	cd/m ²
Wavelength	λр	IF=220 mA	571	-	576	nm
Luminous Intensity (without LCD)	N	IF=220 mA	160	200	-	cd/m ²
Color	Yellow-green					



2. MODULE STRUCTURE

2.1 Counter Drawing

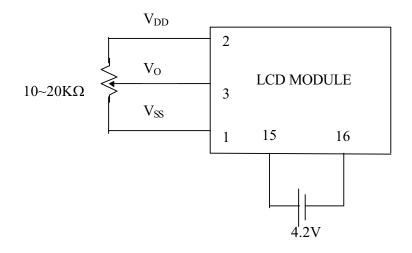




2.2 Interface Pin Description

Pin No.	Symbol	Signal Description		
1	Vss	Signal ground (GND)		
2	Vdd	Power Supply for logic (VDD> VSS)		
3	Vo	Operating Voltage for LCD (variable)		
		Register Selection input		
4	RS	High = Data register		
4	KS	Low = Instruction register (for write)		
		Busy flag address counter (for read)		
5		R/W signal input is used to select the read/write mode		
<u> </u>	R/W	High = Read mode, Low = Write mode		
6	Е	Start enable signal to read or write the data		
		Four low order bi-directional three-state data bus lines.		
7~10	DB0 ~ DB3	Used		
/~10		For data transfer between the MPU and the LCD module.		
		These four are not used during 4-bit operation.		
		Four high order bi-directional three-state data bus lines.		
11~14	DB4~DB7	Used for data transfer between the MPU and the LCD		
11~14	DD4~DD/	module.		
		DB7 can be used as a busy flag.		
15	A	LED backlight drive voltage		
16	K	LED backlight ground		

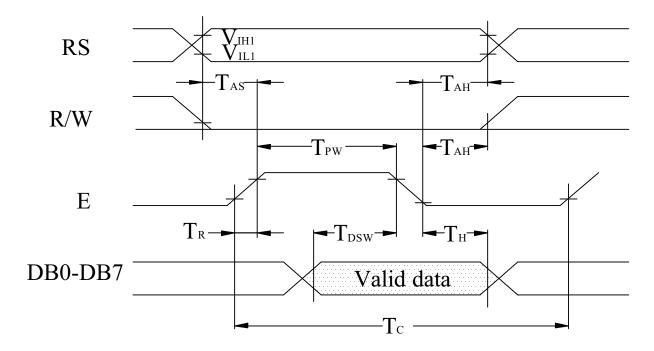
Contrast Adjust



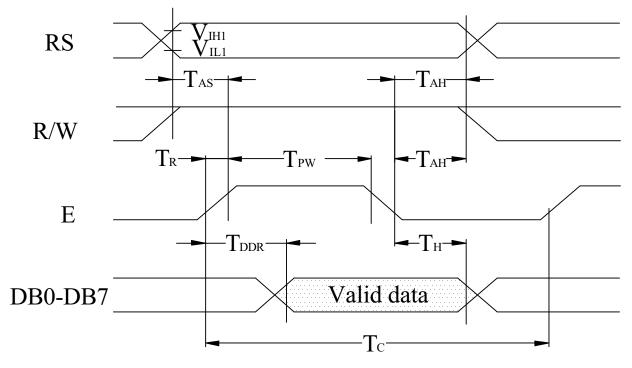


2.3 Timing Characteristics

• Writing data from MPU to ST7066U



• Reading data from ST7066U to MPU





• Write Mode (Writing data from MPU to ST7066U)

 $(V_{cc} = +5V, Ta=25^{\circ}C)$

Symbol	Characteristics	Test Condition	Min.	Тур.	Max.	Unit
$T_{\rm C}$	Enable Cycle Time	Pin E	1200	-	-	ns
T_{PW}	Enable Pulse Width	Pin E	140	-	-	ns
T_R, T_F	Enable Rise / Fall Time	Pin E	-	-	25	ns
T_{AS}	Address Setup Time	Pins: RS , RW,E	0	-	-	ns
T _{AH}	Address Hold Time	Pins :RS,RW,E	10	-	-	ns
T _{DSW}	Data Setup Time	Pins:DB0~DB7	40	-	-	ns
T_{H}	Data Hold Time	Pins:DB0~DB7	10	-	-	ns

• Read Mode (Reading data from ST7066U to MPU)

 $(V_{cc} = +5V, Ta=25^{\circ}C)$

Symbol	Characteristics	Test Condition	Min.	Тур.	Max.	Unit
$T_{\rm C}$	Enable Cycle Time	Pin E	1200	-	-	ns
T_{PW}	Enable Pulse Width	Pin E	140	-	-	ns
T_R, T_F	Enable Rise / Fall Time	Pin E	-	-	25	ns
T_{AS}	Address Setup Time	Pins: RS , RW,E	0	-	-	ns
T _{AH}	Address Hold Time	Pins :RS,RW,E	10	-	-	ns
T_{DDR}	Data Setup Time	Pins:DB0~DB7	-	-	100	ns
T_{H}	Data Hold Time	Pins:DB0~DB7	10	-	-	ns



2.4 Display Command

		Instruction Code					Code					Description
Instructions	ns RS R		DB	DB	DB	DB	DB	DB	DB	DB	Description	Time (270KHz)
Clear Display	0	0	7 0	0	0	0	0	0	0	1	Write "20H" to DDRAM. and set DDRAM address to "00H" from	1.52ms
Return Home	0	0	0	0	0	0	0	0	1	×	AC. Set DDRAM address to "00H" from AC and return cursor to it's original position if shifted. The contents of DDRAM are not changed.	1.52ms
Entry Mode Set	0	0	0	0	0	0	0	1	I/D	S	Sets cursor move direction and specifies display shift. These operations are performed during data write and read.	
Display ON/OFF	0	0	0	0	0	0	1	D	С	В	D=1 : entire display on C=1 : cursor on B=1 : cursor position on	37µs
Cursor or Display Shift	0	0	0	0	0	1	S/C	R/L	×	×	Set cursor moving and display shift control bit, and the direction, without changing of DDRAM data.	37µs
Function Set	0	0	0	0	1	DL	N	F	×	×	DL: interface data is 8/4 bits NL: number of line is 2/1 F: font size is 5×11/5×8	37µs
Set CGRAM Address	0	0	0	1	AC 5	AC 4	AC 3	AC 2	AC 1	AC 0	Set CGRAM address in address counter.	37µs
Set DDRAM Address	0	0	1	AC 6	AC 5	AC 4	AC 3	AC 2	AC 1	AC 0	Set DDRAM address in address counter.	37µs



Read Busy Flag and Address	0	1	BF	AC 6	AC 5	AC 4	AC 3	AC 2	AC 1	AC 0	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.	0µs
Write Data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data into internal RAM (DDRAM/CGRAM).	37µs
Read Data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Read data from internal RAM (DDRAM/CGRAM).	37µs

Note:

Be sure the ST7066U is not in the busy state (BF=0) before sending an instruction from the MPU to the ST7066.

If an instruction is sent without checking the busy flag, the time between the first instruction and next instruction will take much longer than the instruction time itself.

Refer to Instruction Table for the list of each instruction execution time .



2.5 Character Pattern

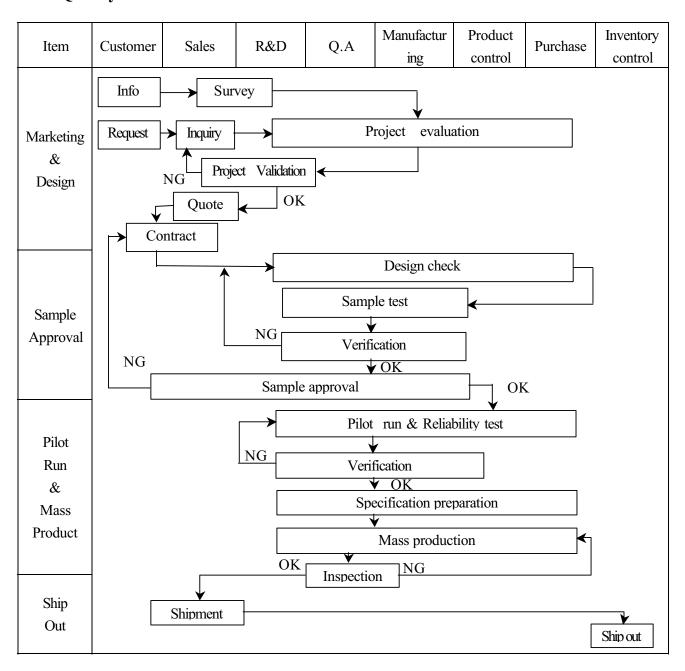
■ CHARACTER PATTERN(SO/HO/EA,WA)

Lower 4 Bits	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	111
xxxx0000	CG RAM (1)					== :	••	: -					-53	≡ .		
xxxx0001	(2)		i.	1.			-===	-:::			===		-	£	-	<u>:::</u>
xxxx0010	(3)		::	:::				! -			E			_:-: [:]		E
xxxx0011	(4)		#		! :	====	:	:≣.					-#-	-	:≝.	::-:
xxxx0100	(5)			::] .				ŧ.			٠.		ŀ.	-	ļi	:::
xxxx0101	(6)		:: :-:::			<u></u> !	::::	II			::	:	:-			i
xxxx0110	(7)		8			I.,!	-ŧ	: <u>.</u> .:			::					E
xxxx0111	(8)		።			Į,j		1,.,1			-:::		[:-:"	-===		H
xxxx1000	(1)		E.			<u> </u>	! :]::: <u>[</u>			- : [-="]		1,1	-,E	:-:
xxxx1001	(2)]:		I		i	•			-:::	"][<u>.</u> .!		:	i
xxxx1010	(3)		:-[-:	==			:	::::					· `-	<u>.</u>		===
xxxx1011	(4)			::		I	! -::	4			:= -		!		:-:	. =:
xxxx1100	(5)		:=	-:			1	i			-[-:-	:::		=		
xxxx1101	(6)						[*]	3-			.::.	:	٠	:	.	<u>:</u>
xxxx1110	(7)		::	<u> </u>		···.]-";							· ·	F	
xxxx1111	(8)			:-						1		·!	-::	=:=		

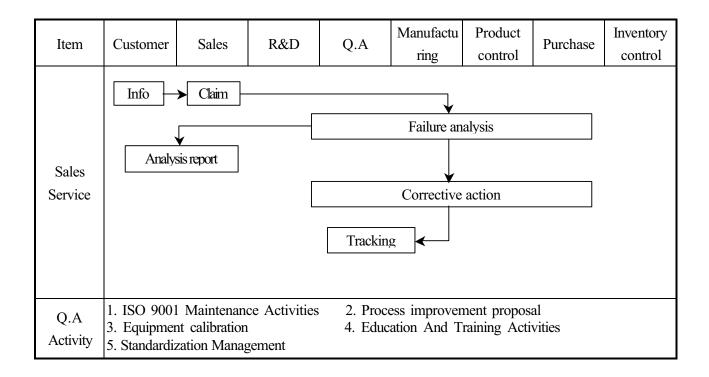


3. QUALITY ASSURANCE SYSTEM

3.1 Quality Assurance Flow Chart









3.2 Inspection Specification

Equipment: Gauge \ MIL-STD \ Powertip Tester \ Sample \ \cdots

IQC Defect Level: Major Defect AQL 0.4; Minor Defect AQL 1.5 °

FQC Defect Level : 100% Inspection \circ OUT Going Defect Level : Sampling \circ

Specification:

NO	Item	Specification	Judge	Level
1	Part Number	The part number is inconsistent with work order of production	N.G.	Major
2	Quantity	The quantity is inconsistent with work order of production	N.G.	Major
	Electronic	The display lacks of some patterns.	N.G.	Major
	characteristics of	Missing line.	N.G.	Major
3	LCM	The size of missing dot, A is $> 1/2$ Dot size	N.G.	Major
	$A=(L+W)\div 2$	There is no function.	N.G.	Major
		Output data is error	N.G.	Major
		Material is different with work order of production	N.G.	Major
		LCD is assembled in inverse direction	N.G.	Major
		Bezel is assembled in inverse direction	N.G.	Major
		Shadow is within LCD viewing area + 0.5 mm	N.G.	Major
	Appearance of	The diameter of dirty particle, A is > 0.4 mm	N.G.	Minor
	LCD	Dirty particle length is $>$ 3.0mm, and 0.01mm $<$ width	N.G.	Minor
1	$A=(L+W)\div 2$	≤0.05mm	14.0.	IVIIIOI
4	Dinter montials	Display is without protective film	N.G.	Minor
	Dirty particle (Including scratch > bubble)	Conductive rubber is over bezel 1mm	N.G.	Minor
		Polarizer exceeds over viewing area of LCD	N.G.	Minor
	scratch bubble)	Area of bubble in polarizer, A>1.0mm, the number of	NIC) f:
		bubble is >1 piece.	N.G.	Minor
		0.4mm <area a<1.0mm,="" bubble="" in="" of="" polarizer,="" td="" the<=""/> <td>21.0</td> <td rowspan="2">Minor</td>	21.0	Minor
		number of bubble is >4 pieces.	N.G.	
		Burned area or wrong part number is on PCB	N.G.	Major
		The symbol, character, and mark of PCB are		
		unidentifiable.	N.G	Minor
		The stripped solder mask, A is > 1.0mm	N.G.	Minor
		0.3mm <stripped <<="" a="" circuit,="" mask="" or="" solder="" td="" visible=""><td></td><td></td></stripped>		
	Appearance of	1.0mm, and the number is ≥ 4 pieces	N.G.	Minor
5	PCB	There is particle between the circuits in solder mask	N.G	Minor
	$A=(L+W)\div 2$	The circuit is peeled off or cracked	N.G	Minor
		There is any circuits risen or exposed.	N.G	Minor
		0.2 mm $<$ Area of solder ball, A is ≤ 0.4 mm		
		The number of solder ball is ≥ 3 pieces	N.G	Minor
		The magnitude of solder ball, A is ≥ 0.4 mm.	N.G	Minor
		THE Magnitude of solder ball, A 15 / U. HIIII.	U.11	IVIIIOI



NO	Item	Specification	Judge	Level
		The shape of modeling is deformed by touching.	N.G.	Major
	Appearance of	Insufficient epoxy: Circuit or pad of IC is visible	N.G.	Minor
6	molding $A=(L+W)\div 2$	Excessive epoxy: Diameter of modeling is >20mm	N.G.	Minor
	$H(L \mid W) \cdot Z$	or height is >2.5mm	NC) (°
		The diameter of pinhole in modeling, A is >0.2mm.	N.G.	Minor
		The folding angle of frame must be $>45 +10$	N.G.	Minor
7	Appearance of frame	The area of stripped electroplate in top-view of frame, A is > 1.0 mm.	N.G.	Minor
/	$A=(L+W)\div 2$	Rust or crack is (Top view only)	N.G.	Minor
		The scratched width of frame is $>$ 0.06mm. (Top view only)	N.G.	Minor
	T1 1	The color of backlight is nonconforming	N.G.	Major
	Electrical	Backlight can't work normally.	N.G.	Major
8	characteristic of	The LED lamp can't work normally	N.G.	Major
8	backlight	The unsoldering area of pin for backlight,	N.G.	Minor
	$A=(L+W)\div 2$	A is $> 1/2$ solder joint area.	N.O.	
	$H(L \mid W) \cdot Z$	The height of solder pin for backlight is $>$ 2.0mm	N.G.	Minor
		The mark or polarity of component is unidentifiable.	N.G.	Minor
		The height between bottom of component and	N.G.	Minor
		surface of the PCB is floating >0.7mm	11.0.	IVIIIOI
10	Assembly parts $A=(L+W) \div 2$	D>1/4W W D D Pad	N.G.	Minor
	A=(L + W) → 2	End solder joint width, D' is >50% width of component termination or width of pad	N.G.	Minor
		Side overhang, D is >25% width of component termination.	N.G.	Minor
		Component is cracked, deformed, and burned, etc.	N.G.	Minor
		The polarity of component is placed in inverse direction.	N.G.	Minor
		Maximum fillet height of solder extends onto the component body or minimum fillet height is <0.5mm.	N.G.	Minor



4. RELIABILITY TEST

4.1 Reliability Test Condition

NO	Item	Test C	Condition					
1	High Temperature Storage	Storage at 80 $\pm 2^{\circ}$ C 96~100 hrs Surrounding temperature, then stora 4hrs	ge at normal condition					
2	Low Temperature Storage	Storage at -30 $\pm 2^{\circ}$ C 96~100 hrs Surrounding temperature, then storage at normal condition 4hrs						
3	High Temperature /Humidity Storage	1.Storage 96~100 hrs 60±2°C, 90~95%RH surrounding temperature, then storage at normal condition 4hrs. (Excluding the polarizer). or 2.Storage 96~100 hrs 40±2°C, 90~95%RH surrounding temperature, then storage at normal condition 4 hrs.						
4	Temperature Cycling	$-20^{\circ}\text{C} \rightarrow 25^{\circ}\text{C} \rightarrow 70^{\circ}\text{C} \rightarrow 25^{\circ}\text{C}$ $(30\text{mins}) (5\text{mins}) (30\text{mins}) (5\text{mins})$ 10 Cycle						
5	Vibration	· ·	minute) 1.5mm tion * (each 2hrs)					
6	ESD Test	Air Discharge: Apply 6 KV with 5 times discharge for each polarity +/- Testing location: Around the face of LCD	Contact Discharge: Apply 250V with 5 times discharge for each polarity +/- Testing location: 1.Apply to bezel. 2.Apply to Vdd, Vss.					
7	Drop Test	Packing Weight (Kg) $0 \sim 45.4$ $45.4 \sim 90.8$ $90.8 \sim 454$ Over 454	Drop Height (cm) 122 76 61 46					



5. PRECAUTION RELATING PRODUCT HANDLING

5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes, please wash it off immediately by using soap and water.

5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module, be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So, please handle it very carefully, do not touch, push or rub the exposed polarizing with anything harder than an HB pencil lead (glass, tweezers, etc.)
 - 5.2.5 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands, this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is $280 \pm 10^{\circ}$ C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM.

5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is 25° C $\pm 5^{\circ}$ C and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush, shake, or jolt the module.

5.4 TERMS OF WARRANTY

5.4.1 Applicable warrant period

The period is within thirteen months since the date of shipping out under normal using and storage conditions.

5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.